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T 04 35 H -

FIG.1: Maximum power dissipation versus RMS on-state current

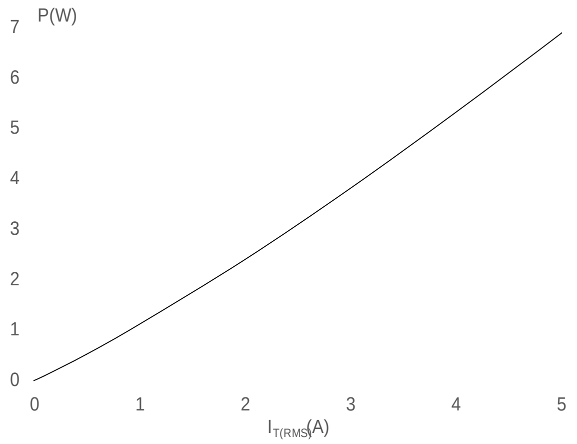

FIG.2: RMS on-state current versus case temperature

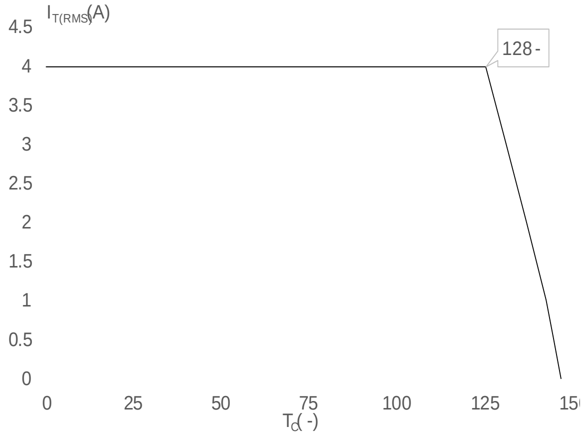

FIG.3: RMS on-state current versus ambient temperature (printed circuit board FR4,copper WKLFNQHVV P IXOO F\FOH

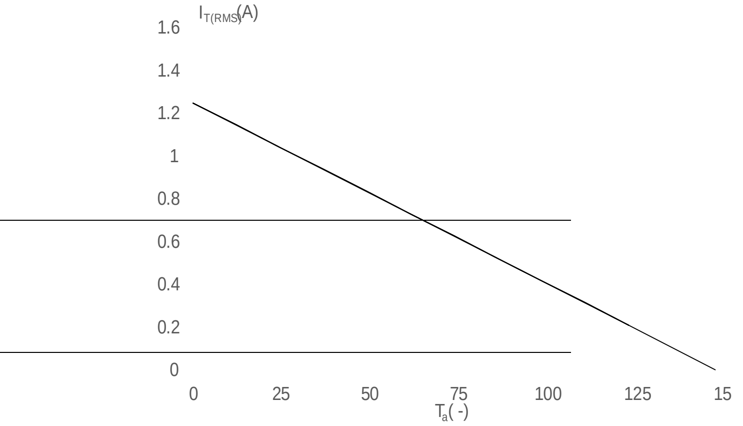

FIG.4: Surge peak on-state current versus number of cycles

FIG.7: Relative variations of gate trigger current, holding current and latching current versus junction temperature

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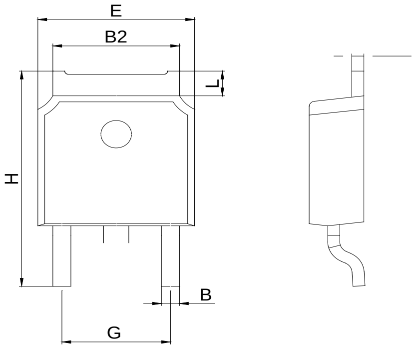
Tw 10R 0.460C 0.49

PACKAGE MECHANICAL DATA



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.15	0		0.006
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1						
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
G1	2.18		2.38	0.086		0.094
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065

DELIVERY MODE